

# **2SK2590** Silicon N Channel MOS FET

REJ03G1021-0300 (Previous: ADE-208-1365A) Rev.3.00 Sep 07, 2005

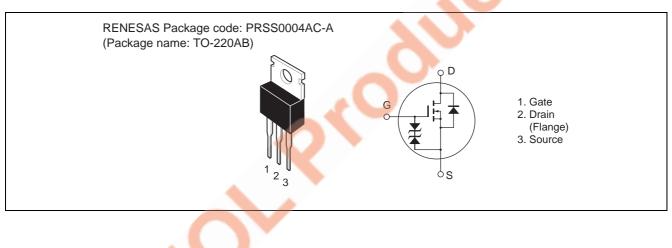
### Application

High speed power switching

### Features

- Low on-resistance
- High speed switching
- Low drive current
- No secondary breakdown
- Suitable for switching regulator, DC-DC converter, motor control

### Outline





# Absolute Maximum Ratings

|                                           |                                      |             | $(Ta = 25^{\circ}C)$ |
|-------------------------------------------|--------------------------------------|-------------|----------------------|
| Item                                      | Symbol                               | Ratings     | Unit                 |
| Drain to source voltage                   | V <sub>DSS</sub>                     | 200         | V                    |
| Gate to source voltage                    | V <sub>GSS</sub>                     | ±20         | V                    |
| Drain current                             | ID                                   | 7           | A                    |
| Drain peak current                        | I <sub>D(pulse)</sub> * <sup>1</sup> | 28          | А                    |
| Body to drain diode reverse drain current | I <sub>DR</sub>                      | 7           | А                    |
| Channel dissipation                       | Pch* <sup>2</sup>                    | 50          | W                    |
| Channel temperature                       | Tch                                  | 150         | °C                   |
| Storage temperature                       | Tstg                                 | -55 to +150 | °C                   |

Notes: 1. PW  $\leq$  10  $\mu$ s, duty cycle  $\leq$  1 %

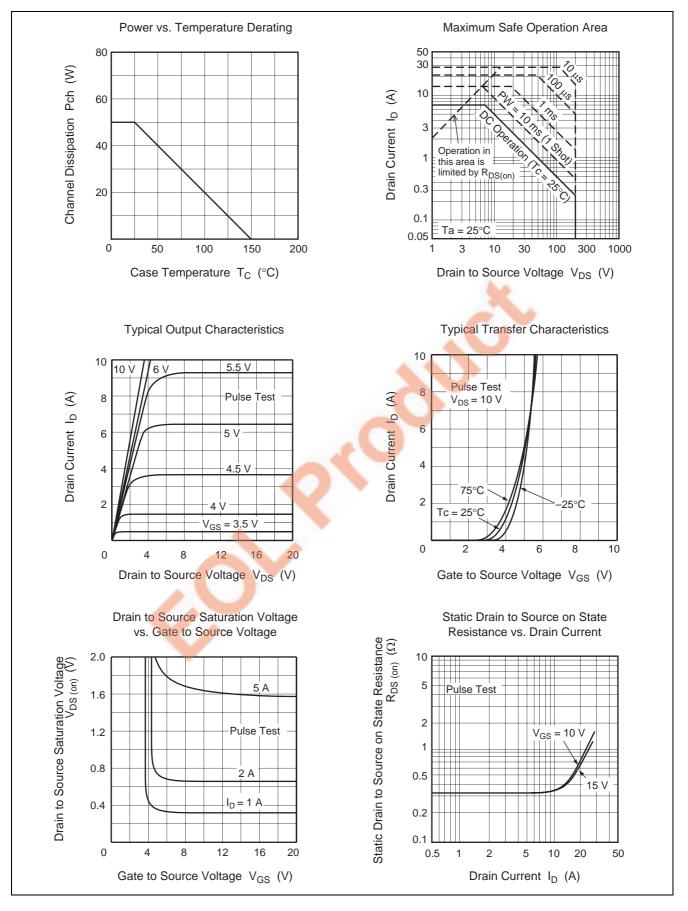
2. Value at  $Tc = 25^{\circ}C$ 

# **Electrical Characteristics**

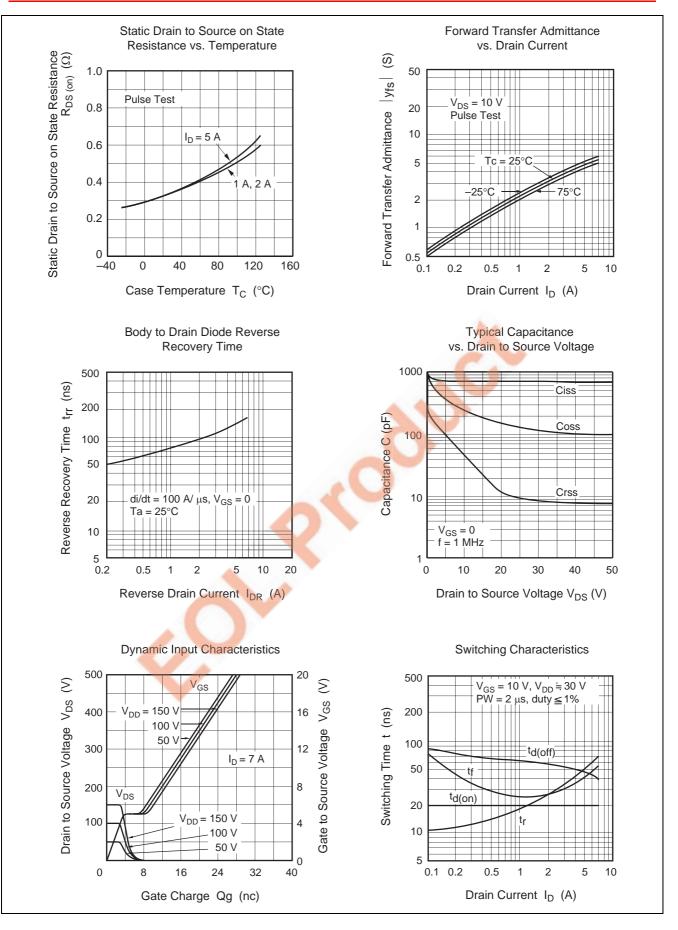
|                                            |                      |     |      |      |      | (Ta = 25°C)                                                                     |
|--------------------------------------------|----------------------|-----|------|------|------|---------------------------------------------------------------------------------|
| ltem                                       | Symbol               | Min | Тур  | Max  | Unit | Test Conditions                                                                 |
| Drain to source breakdown voltage          | V <sub>(BR)DSS</sub> | 200 | _    | —    | V    | $I_{D} = 10 \text{ mA}, V_{GS} = 0$                                             |
| Gate to source breakdown voltage           | V <sub>(BR)GSS</sub> | ±20 | _    | —    | V    | $I_{G} = \pm 100 \ \mu A, \ V_{DS} = 0$                                         |
| Gate to source leak current                | I <sub>GSS</sub>     |     | -    | ±10  | μA   | $V_{GS} = \pm 16 \text{ V}, \text{ V}_{DS} = 0$                                 |
| Zero gate voltage drain current            | I <sub>DSS</sub>     | _   | —    | 250  | μA   | $V_{DS}$ =160 V, $V_{GS}$ = 0                                                   |
| Gate to source cutoff voltage              | V <sub>GS(off)</sub> | 2.0 | —    | 4.0  | V    | $I_D = 1 \text{ mA}, V_{DS} = 10 \text{ V}$                                     |
| Static drain to source on state resistance | R <sub>DS(on)</sub>  | _   | 0.33 | 0.45 | Ω    | $I_D = 4 A, V_{GS} = 10 V^{*1}$                                                 |
| Forward transfer admittance                | y <sub>fs</sub>      | 3.0 | 4.5  | ) -  | S    | $I_D = 4 \text{ A}, V_{DS} = 10 \text{ V}^{*1}$                                 |
| Input capacitance                          | Ciss                 | _   | 700  | _    | pF   | $V_{DS} = 10 V, V_{GS} = 0,$                                                    |
| Output capacitance                         | Coss                 | F   | 260  | —    | pF   | f = 1 MHz                                                                       |
| Reverse transfer capacitance               | Crss                 | V   | 45   | —    | pF   |                                                                                 |
| Turn-on delay time                         | t <sub>d(on)</sub>   |     | 20   | —    | ns   | $I_D = 4 \text{ A}, V_{GS} = 10 \text{ V},$<br>$R_L = 7.5 \Omega$               |
| Rise time                                  | tn                   | _   | 45   | —    | ns   |                                                                                 |
| Turn-off delay time                        | t <sub>d(off)</sub>  |     | 50   | —    | ns   |                                                                                 |
| Fall time                                  | tr                   | -   | 35   | —    | ns   |                                                                                 |
| Body to drain diode forward voltage        | VDF                  | _   | 1.1  | —    | V    | $I_F = 7 \text{ A}, V_{GS} = 0$                                                 |
| Body to drain diode reverse recovery time  | t <sub>rr</sub> *    | _   | 150  | —    | ns   | I <sub>F</sub> = 7 A, V <sub>GS</sub> = 0,<br>di <sub>F</sub> / dt = 100 A / μs |
| Note: 3. Pulse Test                        |                      |     |      |      |      |                                                                                 |



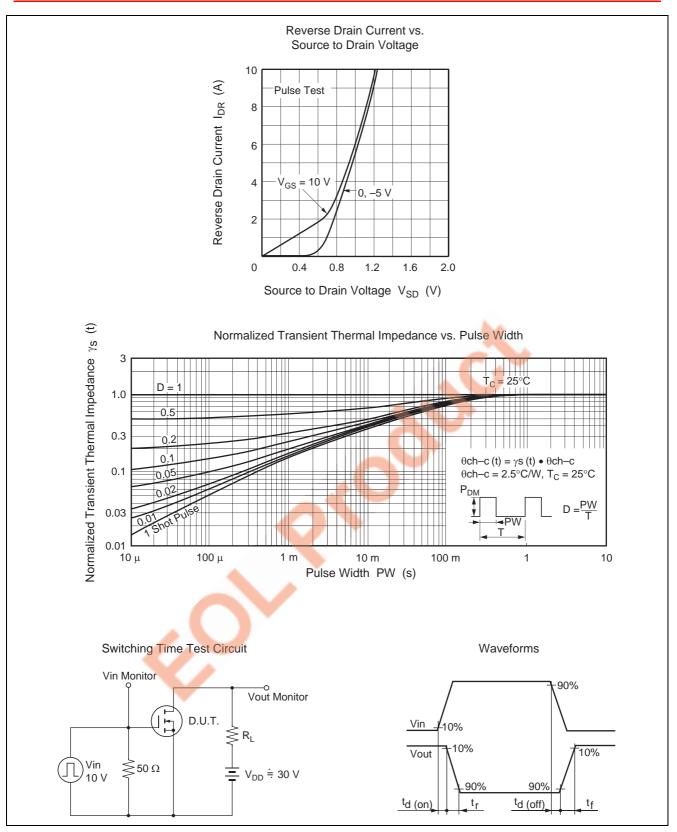
### **Main Characteristics**



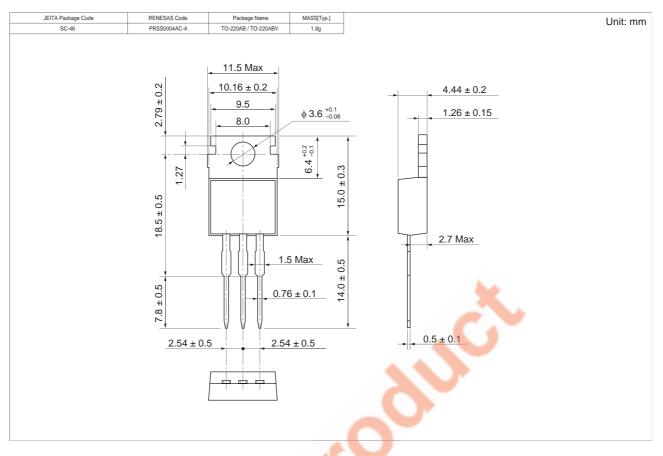








### **Package Dimensions**



### **Ordering Information**

| Part Name | Quantity | Shipping Container |
|-----------|----------|--------------------|
| 2SK2590-E | 500 pcs  | Box (Sack)         |

Note: For some grades, production may be terminated. Please contact the Renesas sales office to check the state of production before ordering the product.



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